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RF MEMS Technology for Fabricating RF MEMS Switches

Tech ID: 18883 / UC Case 2002-369-0

TECHNOLOGY DESCRIPTION

University researchers have invented a low-cost, high performance, and substrate independent RF MEMS technology for RF MEMS switch fabrication with high yield and reliability. It is compatible with well established printed circuit board (PCB) technology and allows the choice of any substrate with desired electrical and mechanical properties for a specific communication application, to enhance its performance and reduce cost.

ADVANTAGES

Utilizing this process for example, allows for the integration of RF MEMS switches and antenna systems thereby creating a MEMS integrated smart antenna system on the same substrate. Since this technology enables the use of microwave laminates, high performance substrates can be chosen for system efficiency. In addition, elimination of interconnects and matching circuits enhance performance at reduced cost. These same advantages can be realized in variable capacitors, on-chip inductors, tunable filters, and tunable RF matching circuits.

PATENT STATUS

Country	Type	Number	Dated	Case
United States Of America	Issued Patent	7,884,689	02/08/2011	2002-369

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OTHER INFORMATION

CATEGORIZED AS

- » **Nanotechnology**
- » Electronics

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